

ABSTRACT

An insulating material comprising a cycloolefin polymer, specifically, an interlayer insulating material
5 for a high-density assembly board having interlayer-
connecting via holes at most 200 μm in diameter,
comprising a cycloolefin polymer containing at least 50
mol% of a repeating unit derived from a cycloolefin
monomer; a dry film formed from a curable resin
10 composition comprising a polymer having a number average
molecular weight within a range of 1,000 to 1,000,000 as
measured by gel permeation chromatography, and a hardener;
and a resin-attached metal foil obtained by forming a film
of a cycloolefin polymer on one side of a metal foil.
15 Laminates, multi-layer laminates and build-up multi-layer
laminates making use of these materials, and production
processes thereof.